



Material Content Data Sheet



Sales Product Name	ESD1P0RFS H6327			Issued		29. August 2013		
MA#	MA000845488							
Package	PG-SOT363-6-3			Weight*		6.46 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		13	
	noble metal	gold	7440-57-5	0.008	0.13		1251	
	inorganic material	silicon	7440-21-3	0.069	1.07	1.20	10680	11944
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		96	
	non noble metal	titanium	7440-32-6	0.003	0.05		481	
	non noble metal	chromium	7440-47-3	0.009	0.14		1442	
	non noble metal	copper	7440-50-8	3.093	47.85	48.05	478539	480558
wire	non noble metal	copper	7440-50-8	0.010	0.15	0.15	1490	1490
encapsulation	organic material	carbon black	1333-86-4	0.030	0.46		4628	
	plastics	epoxy resin	-	0.643	9.95		99501	
	inorganic material	silicondioxide	60676-86-0	2.318	35.87	46.28	358666	462795
leadfinish	non noble metal	tin	7440-31-5	0.213	3.30	3.30	32993	32993
plating	noble metal	silver	7440-22-4	0.066	1.02	1.02	10220	10220
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com